

Surface Mount Yellow Green/ Yellow Chip LED - 0805

multicomp PRO

**RoHS
Compliant**



Features

- 2mm × 1.25mm SMT LED, 0.7mm Thickness.
- Wide Viewing Angle.
- Ideal for Backlight and Indicator.
- Various Colours and Lens types Available.

Applications

- Automotive: Backlighting in dashboard and switch.
- Telecommunication: Indicator and Backlighting in telephone and fax.
- Flat Backlight for LCD switch and symbol.

Device Selection Guide

Part No.	Chip		Lens Colour
	Material	Emitted Colour	
MP005935	(InGaAlP)	Yellow	Water Clear
	(InGaAlP)	Green	

Absolute Maximum Ratings at TA=25°C

Parameter	Symbol	Green	Yellow	Unit
Power Dissipation	P _D	62		mW
Forward Current	I _F	25		mA
Peak Forward Current*1	I _{FP}	100		mA
Reverse Voltage	V _R	5		V
Operating Temperature	T _{opr}	-40°C To +85°C		
Storage Temperature	T _{stg}	-40°C To +85°C		

Notes:

*1: Pulse width ≤ 0.1ms, Duty cycle ≤ 1/10

Electrical / Optical Characteristics at TA=25°C

Parameter	Symbol	Device	Min.	Typ.	Max	Unit	Test Conditions
Forward Voltage	V _F	Green Yellow	—	2.2 2.2	2.5 2.5	V	I _F =20mA
Reverse Current	I _R		—	—	10	μA	V _R =5V
Dominant Wavelength	λ _D		568 586	—	576 594	nm	I _F =20mA
Luminous Intensity	I _v		28 62	—	80 170	mcd	I _F =20mA
Viewing Angle	2θ _{1/2}		—	120	—	Deg.	I _F =20mA

Remarks:

If special sorting is required (e.g. binning based on forward voltage, luminous intensity, or chromaticity), the typical accuracy of the sorting process is as follows:

1. wavelength: ±1nm
2. Luminous Intensity: ±15%
3. Forward Voltage: ±0.1V

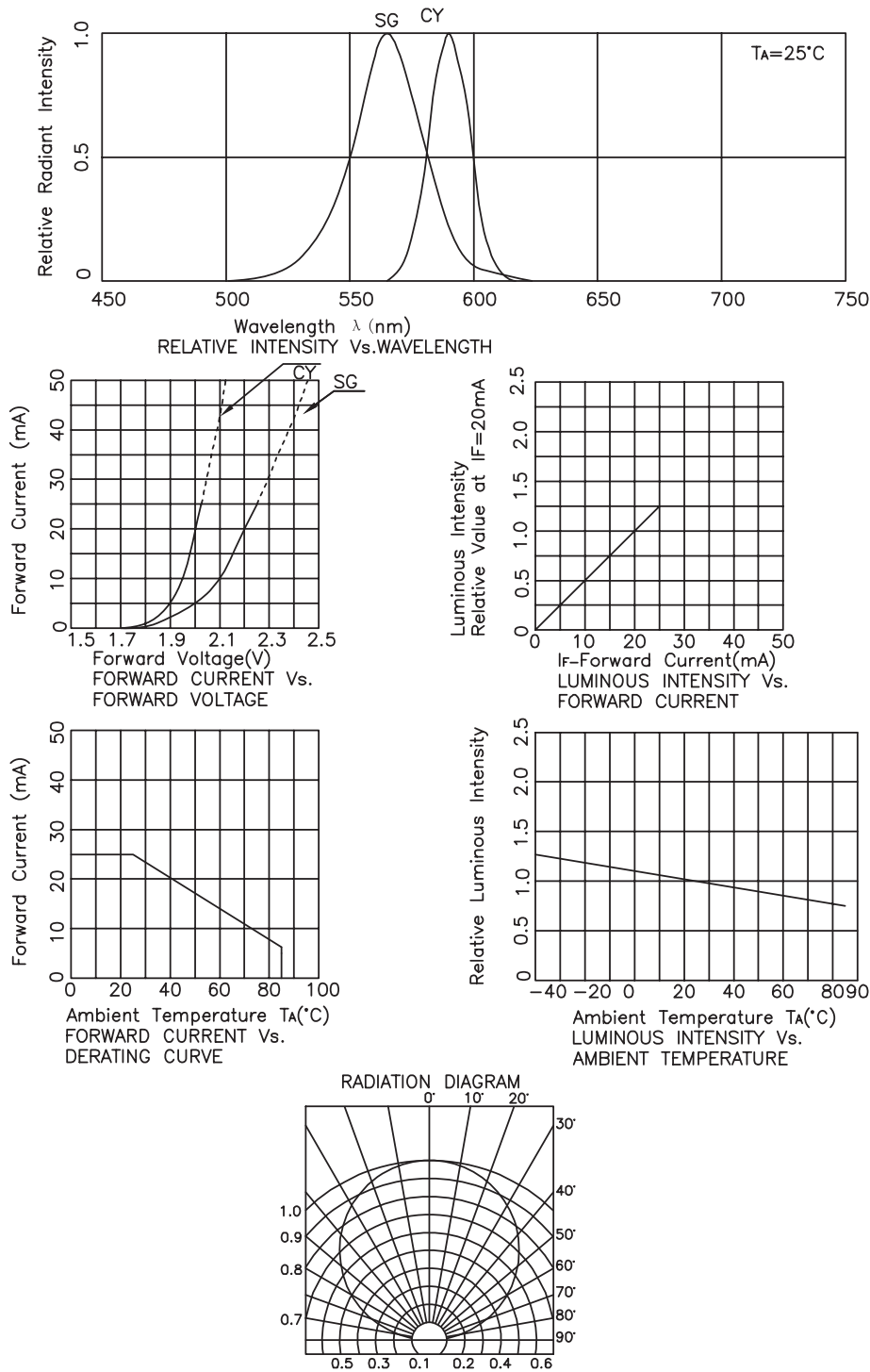
Newark.com/multicomp-pro
Farnell.com/multicomp-pro
Element14.com/multicomp-pro

multicomp PRO

Surface Mount Yellow Green/ Yellow Chip LED - 0805

multicomp PRO

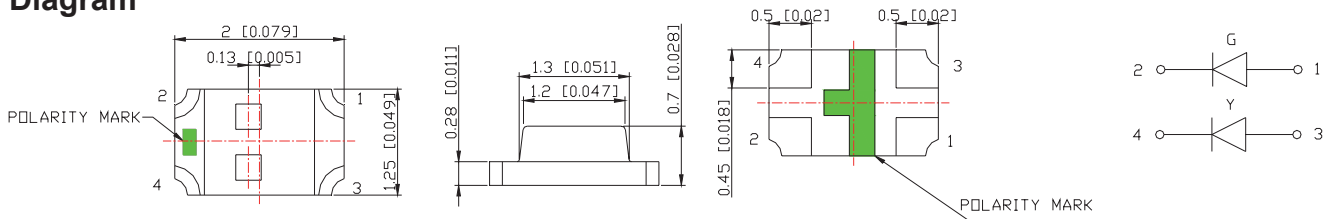
Typical Electrical/Optical Characteristics Curves



Surface Mount Yellow Green/ Yellow Chip LED - 0805

multicomp PRO

Diagram

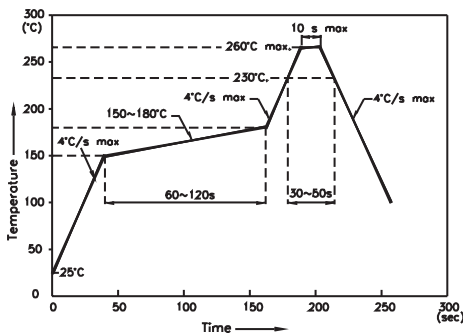


Notes:

1. All dimensions are in millimeters.
2. Tolerance is ± 0.15 unless otherwise noted.
3. Specifications are subject to change without notice.

Soldering Profile

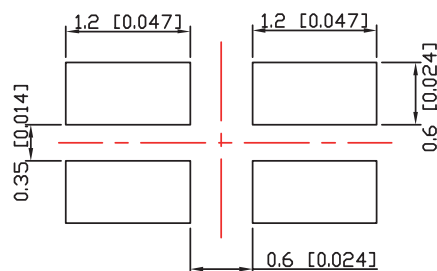
Reflow Soldering Profile For Lead-free SMT Process.



Notes

1. We recommend the reflow temperature 245°C. ($\pm 5^\circ\text{C}$) The maximum soldering temperature should be limited to 260°C.
2. Don't cause stress to epoxy resin while it is exposed to high temperature.
3. Number of reflow process shall be 2 times or less.

Recommended Soldering Pattern



Part Number Table

Description	Part Number
SMD Chip LED, 0805, Yellow Green / Yellow, 80/170mcd, 120°	MP005935

Important Notice : This data sheet and its contents (the "Information") belong to the members of the AVNET group of companies (the "Group") or are licensed to it. No licence is granted for the use of it other than for information purposes in connection with the products to which it relates. No licence of any intellectual property rights is granted. The Information is subject to change without notice and replaces all data sheets previously supplied. The Information supplied is believed to be accurate but the Group assumes no responsibility for its accuracy or completeness, any error in or omission from it or for any use made of it. Users of this data sheet should check for themselves the Information and the suitability of the products for their purpose and not make any assumptions based on information included or omitted. Liability for loss or damage resulting from any reliance on the Information or use of it (including liability resulting from negligence or where the Group was aware of the possibility of such loss or damage arising) is excluded. This will not operate to limit or restrict the Group's liability for death or personal injury resulting from its negligence. Multicomp Pro is the registered trademark of Premier Farnell Limited 2019.

Newark.com/multicomp-pro
Farnell.com/multicomp-pro
Element14.com/multicomp-pro

multicomp PRO